

ABSTRACT OF THE DISCLOSURE

A method and system for processing wafers is disclosed. According to one embodiment (100) a chuck system (102) may be situated opposite to an input source (104). A chuck system (102) may apply a force (e.g., mechanical and/or electromagnetic) that deforms a substrate (108). Once deformed, essentially all of a substrate (108) may be oriented at a predetermined angle (e.g., 90°) with respect to an input source (104).

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